



HM4033

PNP EPITAXIAL PLANAR TRANSISTOR

Description

The HM4033 is designed for high current general purpose amplifier applications.

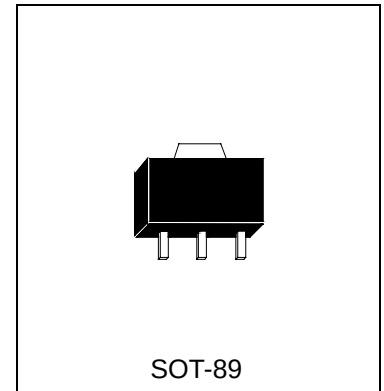
Absolute Maximum Ratings

- Maximum Temperatures
Storage Temperature -55 ~ +150 °C
Junction Temperature +150 °C Maximum
- Maximum Power Dissipation
Total Power Dissipation (Ta=25°C) 1.2 W
- Maximum Voltages and Currents (Ta=25°C)
VCBO Collector to Base Voltage -80 V
VCEO Collector to Emitter Voltage -80 V
VEBO Emitter to Base Voltage -5 V
IC Collector Current -1 A

Characteristics (Ta=25°C)

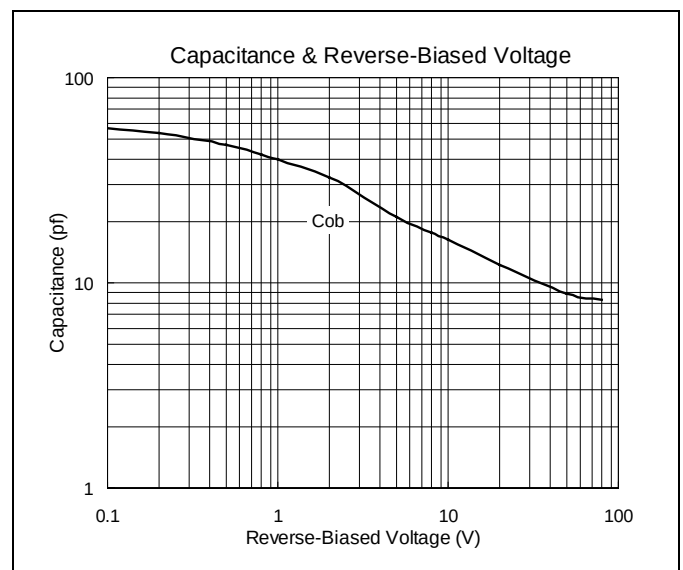
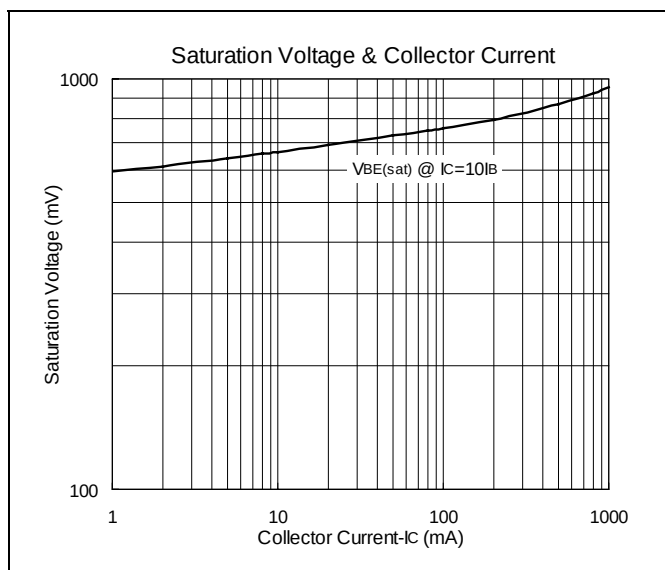
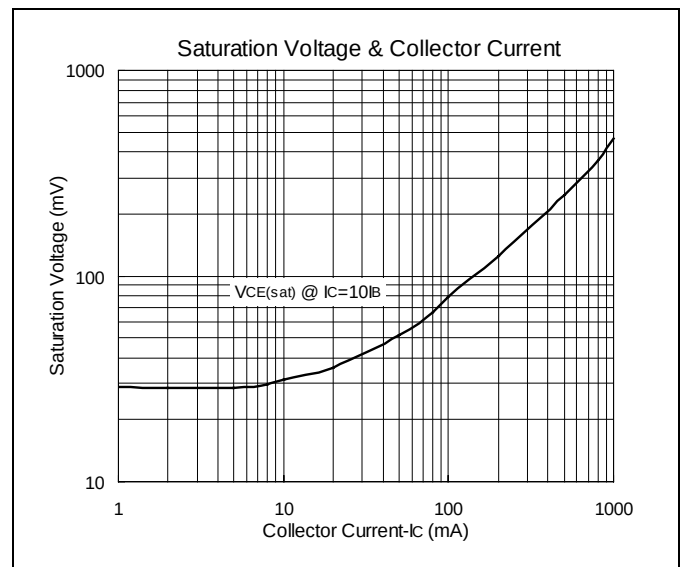
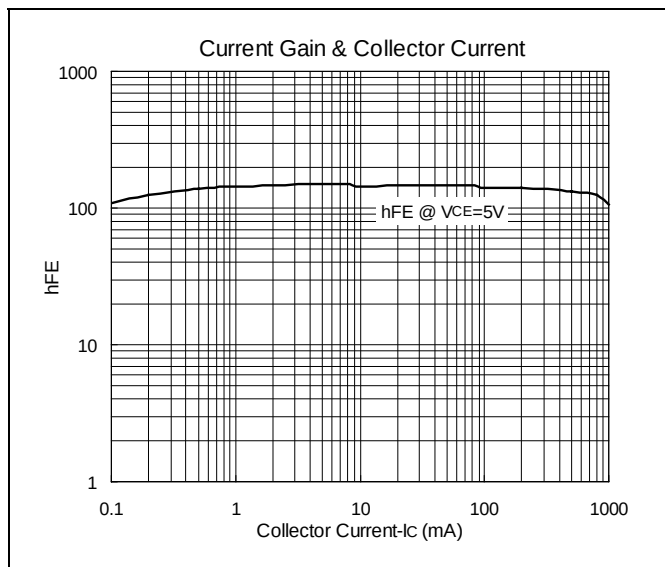
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-80	-	-	V	IC=-10uA, IE=0
BVCEO	-80	-	-	V	IC=-10mA, IB=0
BVEBO	-5	-	-	V	IC=-10uA, IC=0
ICBO	-	-	-100	nA	VCB=-60V, IE=0
IEBO	-	-	-100	nA	VEB=-5V, IC=0
*VCE(sat)1	-	-	-150	mV	IC=-150mA, IB=-15mA
*VCE(sat)2	-	-	-500	mV	IC=-500mA, IB=-50mA
*VBE(sat)1	-	-	-900	mV	IC=-150mA, IB=-15mA
*VBE(sat)2	-	-	-1.1	V	IC=-500mA, IB=-50mA
*hFE1	75	-	-		VCE=-5V, IC=-0.1mA
*hFE2	100	-	-		VCE=-5V, IC=-100mA
*hFE3	70	-	-		VCE=-5V, IC=-500mA
*hFE4	25	-	-		VCE=-5V, IC=-1A
fT	100	-	-	MHz	VCE=-10V, IC=-50mA, f=100MHz
Cob	-	-	20	pF	VCB=-10V, IE=0, f=1MHz

*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%



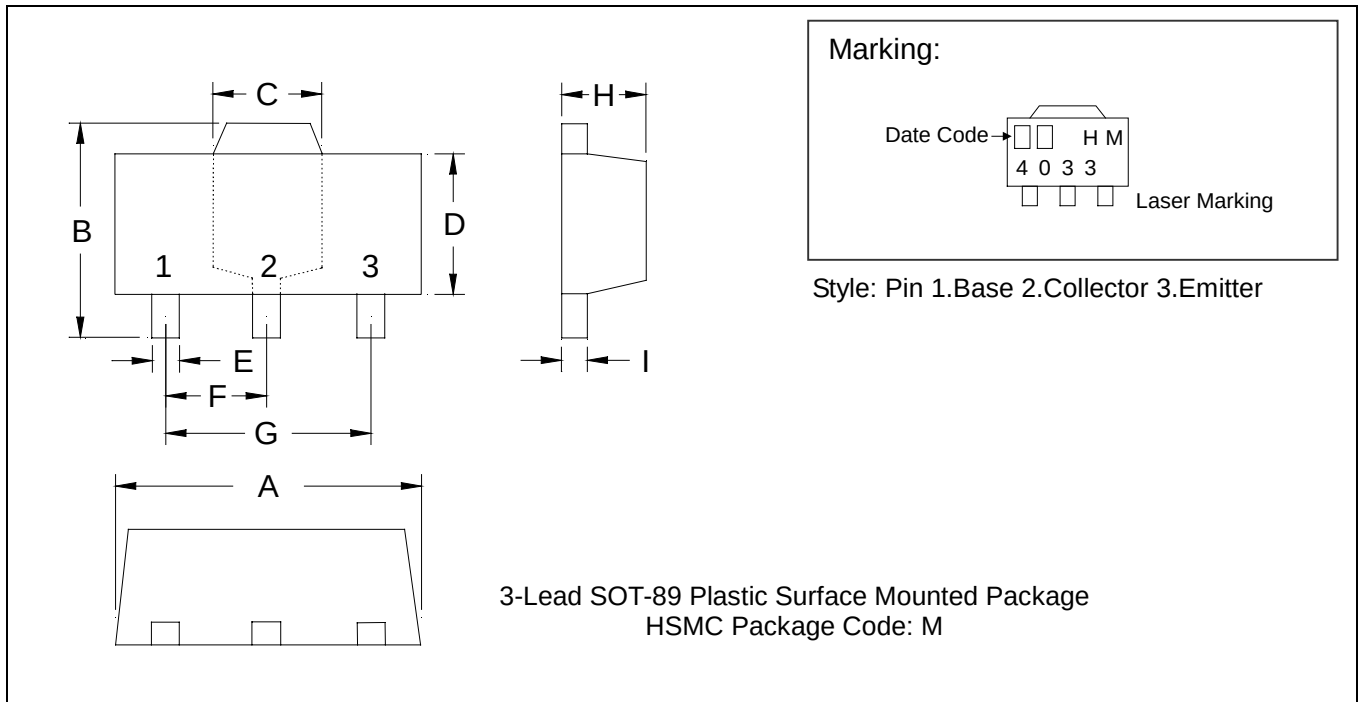


Characteristics Curve





SOT-89 Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1732	0.1811	4.40	4.60	F	0.0583	0.0598	1.48	1.52
B	0.1594	0.1673	4.05	4.25	G	0.1165	0.1197	2.96	3.04
C	0.0591	0.0663	1.50	1.70	H	0.0551	0.0630	1.40	1.60
D	0.0945	0.1024	2.40	2.60	I	0.0138	0.0161	0.35	0.41
E	0.0141	0.0201	0.36	0.51					

Notes: 1.Dimension and tolerance based on our Spec. dated May. 05,1996.

2.Controlling dimension: millimeters.

3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.

4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material:

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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Head Office And Factory:

- **Head Office** (Hi-Sincerity Microelectronics Corp.): 10F.,No. 61, Sec. 2, Chung-Shan N. Rd. Taipei Taiwan R.O.C.
Tel: 886-2-25212056 Fax: 886-2-25632712, 25368454
- **Factory 1:** No. 38, Kuang Fu S. Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C
Tel: 886-3-5983621~5 Fax: 886-3-5982931